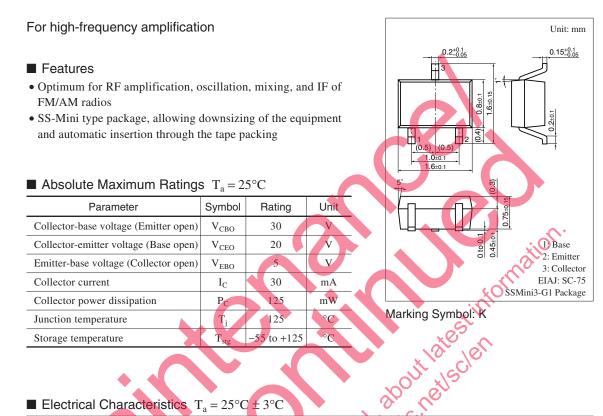
# **2SC4655**

### Silicon NPN epitaxial planar type

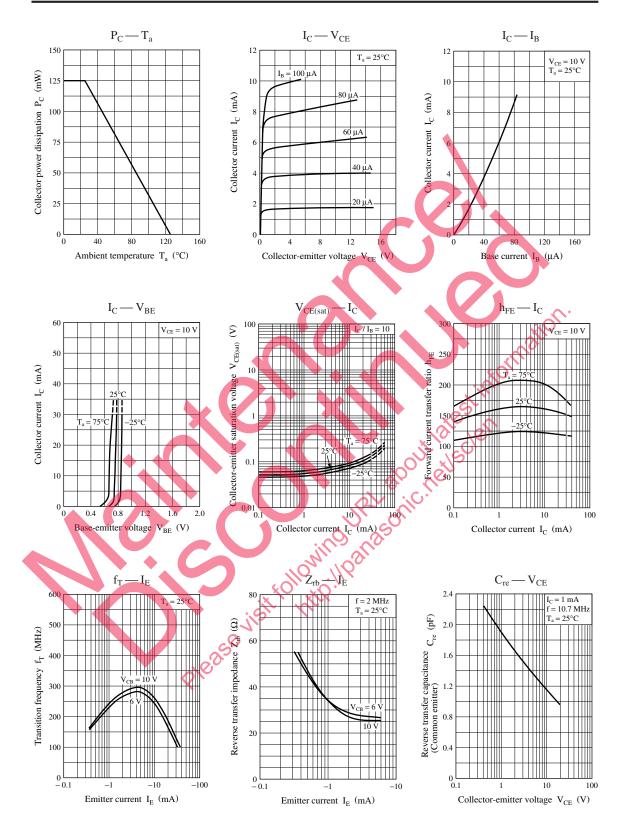


#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

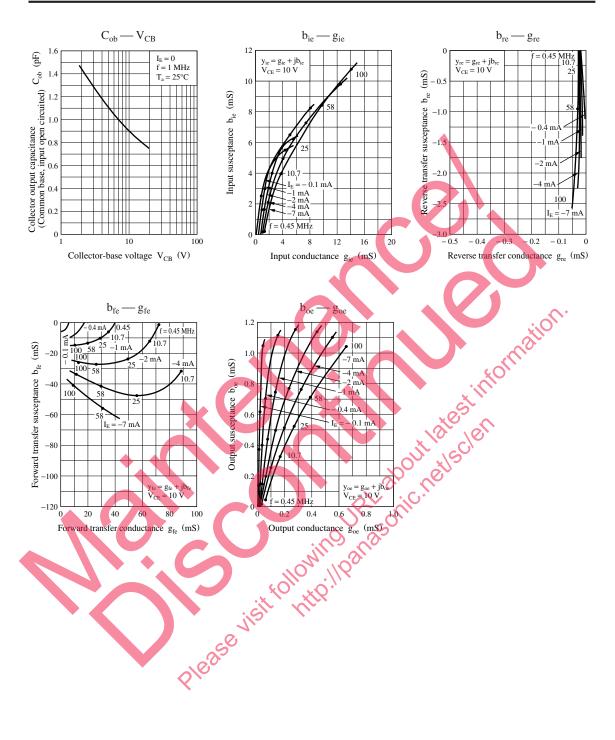
| Parameter                             | Symbol           | Conditions                                     | Min | Тур | Max | Unit |
|---------------------------------------|------------------|--|-----|-----|-----|------|
| Collector-base voltage (Emitter open) | V <sub>CBO</sub> | $I_{\rm C} = 10 \ \mu \text{A}, I_{\rm E} = 0$ | 30  |     |     | V    |
| Collector-emitter voltage (Base open) | V <sub>CEO</sub> | $I_{\rm C} = 2 \text{ mA}, I_{\rm B} = 0$      | 20  |     |     | V    |
| Emitter-base voltage (Collector open) | V <sub>EBO</sub> | $I_{\rm E} = 10 \mu A$ , $I_{\rm C} = 00$      | 5   |     |     | V    |
| Forward current transfer ratio *      | h <sub>FE</sub>  | $V_{CE} = 10 \text{ V}, I_{C} = 1 \text{ mA}$  | 70  |     | 250 | _    |
| Transition frequency                  | $f_{T}$          | $V_{CB} = 10$ V, $I_E = -1$ mA, f = 200 MHz    | 150 | 230 |     | MHz  |
| Reverse transfer capacitance          | C <sub>re</sub>  | $V_{CB} = 10$ V, $I_E = -1$ mA, $f = 10.7$ MHz |     | 1.3 |     | pF   |
| (Common emitter)                      | Le               |  |     |     |     |      |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors. ~0 2. \*: Rank classification

| Rank     | В         | С          |  |  |
|----------|-----------|------------|--|--|
| $h_{FE}$ | 70 to 160 | 110 to 250 |  |  |



## Panasonic



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